SamHop Microelectronics Corp.

STS8205

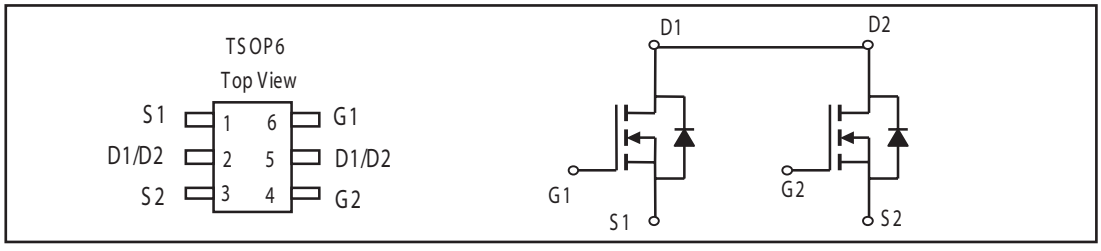
Jun,08 2005 ver 1.4

Dual N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
V_{DSS}	I_D	$R_{DS(ON)}$ (mΩ) Max
20V	4A	30 @ V_{GS} = 4.0V 46 @ V_{GS} = 2.5V

FEATURES

- Super high dense cell design for low $R_{DS(ON)}$.
- Rugged and reliable.
- Surface Mount Package.



ABSOLUTE MAXIMUM RATINGS (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	±10	V
Drain Current-Continuous @ T_J=25°C	I_D	4	A
-Pulsed [b]	I_{DM}	25	A
Drain-Source Diode Forward Current [a]	I_S	2	A
Maximum Power Dissipation [a]	P_D	1.25	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient [a]	$R_{\theta JA}$	100	°C/W

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ELECTRICAL CHARACTERISTICS (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ [c]	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V, I_D=250uA	20			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=16V, V_{GS}=0V			1	uA
Gate-Body Leakage	I_{GSS}	V_{GS}=± 10V,V_{DS}=0V			±100	nA
ON CHARACTERISTICS [b]						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250uA	0.5	0.8	1.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=4.0V, I_D=4A		27	30	m ohm
		V_{GS}=2.5V, I_D=3A		35	46	m ohm
Forward Transconductance	g_{FS}	V_{DS}=5V, I_D=4A		13		S
DYNAMIC CHARACTERISTICS [c]						
Input Capacitance	C_{ISS}	V_{DS}=8V, V_{GS}=0V f=1.0MHz		800		pF
Output Capacitance	C_{OSS}			155		pF
Reverse Transfer Capacitance	C_{RSS}			125		pF
SWITCHING CHARACTERISTICS [c]						
Turn-On Delay Time	$t_{D(ON)}$	V_{DD}=10V, I_D=1A, V_{GEN}=4.0V, R_L=10 ohm R_{GEN}=10 ohm		18.3		ns
Rise Time	t_r			4.8		ns
Turn-Off Delay Time	$t_{D(OFF)}$			43.5		ns
Fall Time	t_f			20		ns
Total Gate Charge	Q_g	V_{DS}=10V, I_D=4A, V_{GS}=4.0V		11		nC
Gate-Source Charge	Q_{gs}			2.2		nC
Gate-Drain Charge	Q_{gd}			2.5		nC

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ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ[c]	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS [b]						
Diode Forward Voltage	V_{SD}	V_{GS} = 0V, Is =2A		0.8	1.2	V

Notes

a.Surface Mounted on FR4 Board, t≤10sec.
b.Pulse Test:Pulse Width≤300us, Duty Cycle≤ 2%.
c.Guaranteed by design, not subject to production testing.

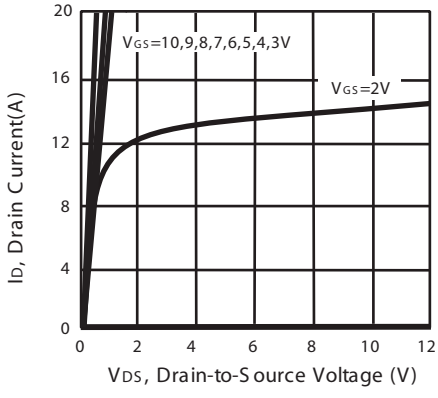


Figure 1. Output Characteristics

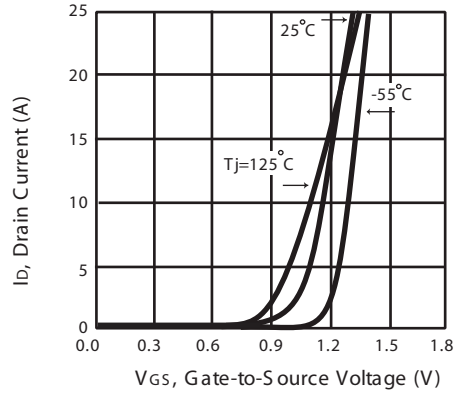


Figure 2. Transfer Characteristics

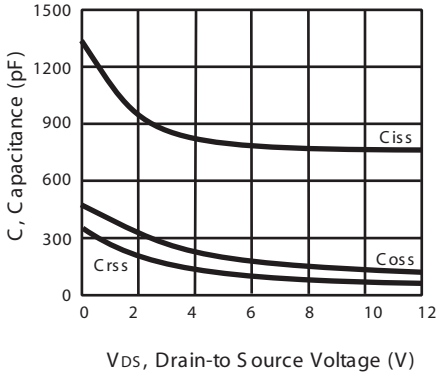


Figure 3. Capacitance

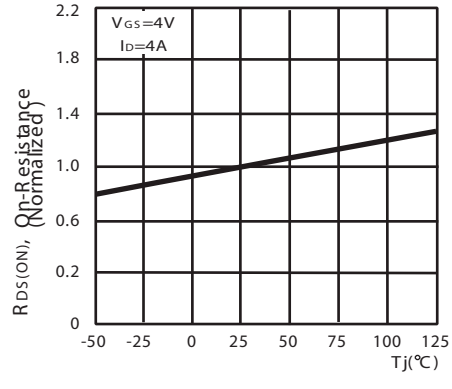
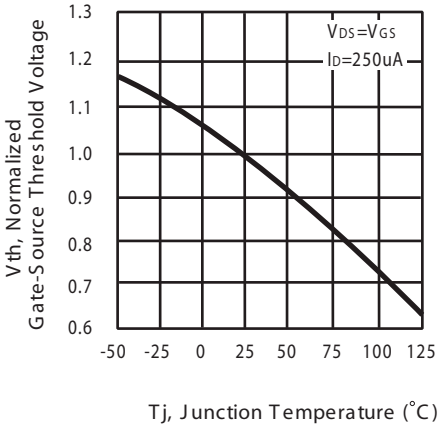


Figure 4. On-Resistance Variation with Temperature



with Temperature

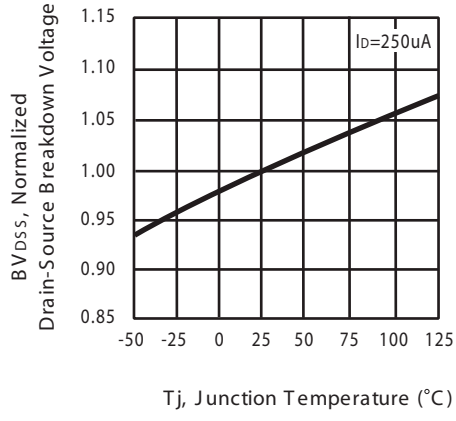


Figure 6. Breakdown Voltage Variation with Temperature

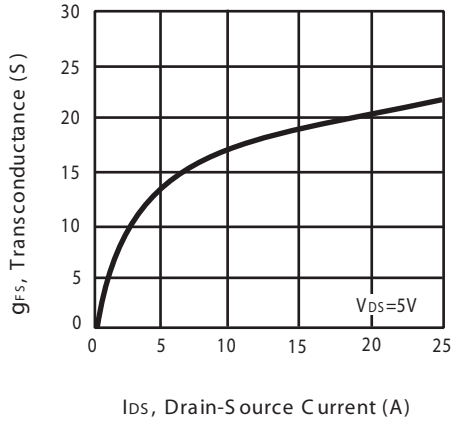


Figure 7. Transconductance Variation with Drain Current

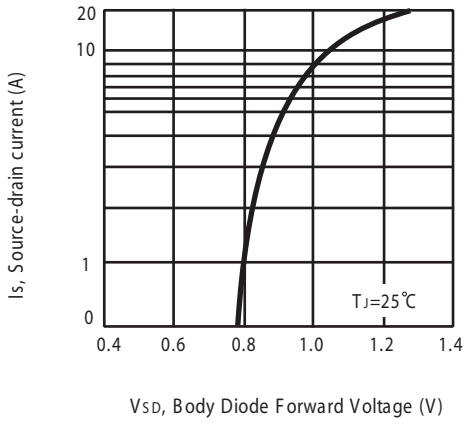


Figure 8. Body Diode Forward Voltage Variation with Source Current

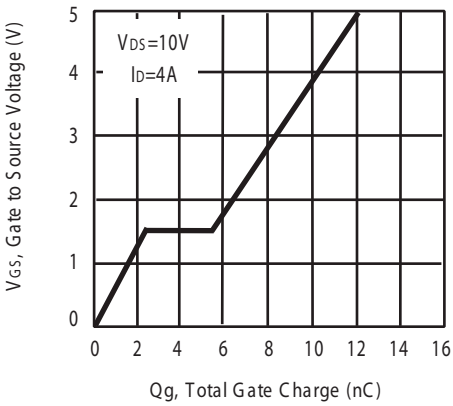


Figure 9. Gate Charge

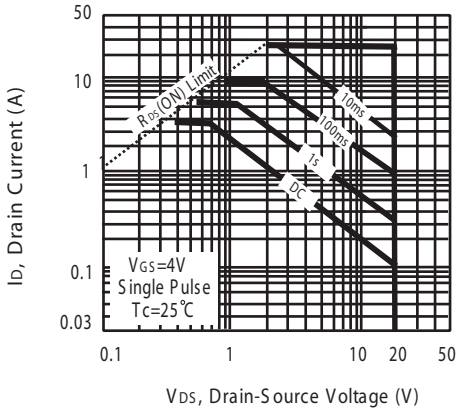


Figure 10. Maximum Safe Operating Area

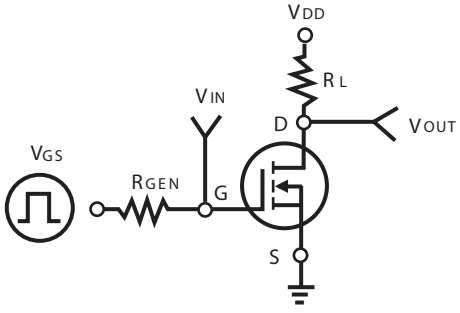


Figure 11. Switching Test Circuit

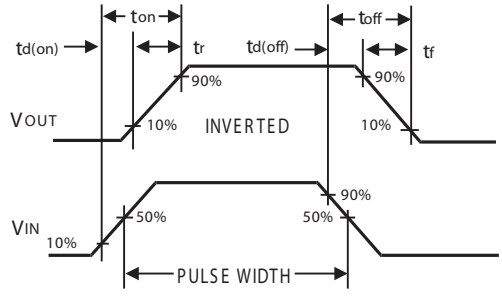
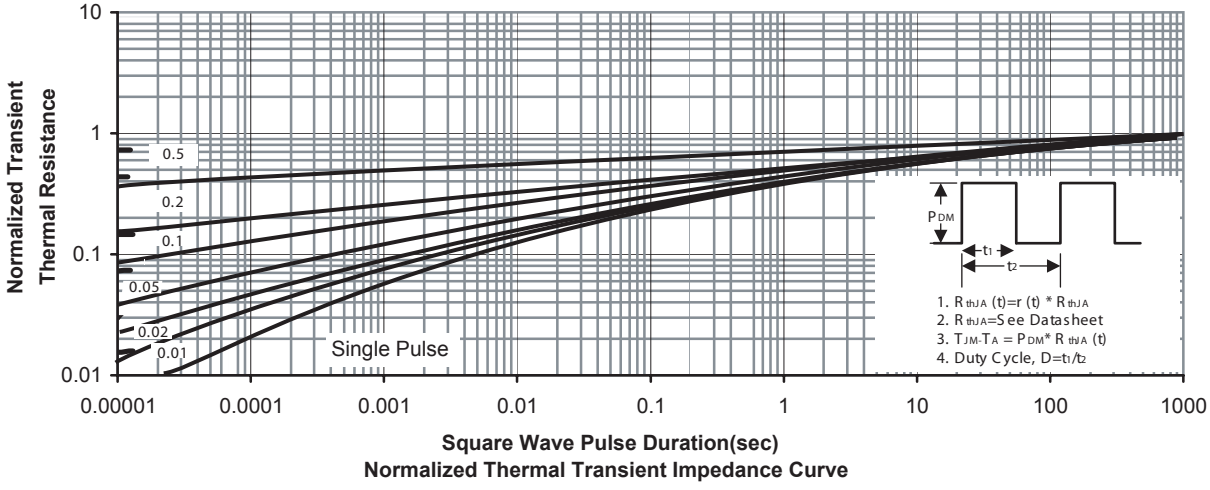


Figure 12. Switching Waveforms



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PACKAGE OUTLINE DIMENSIONS

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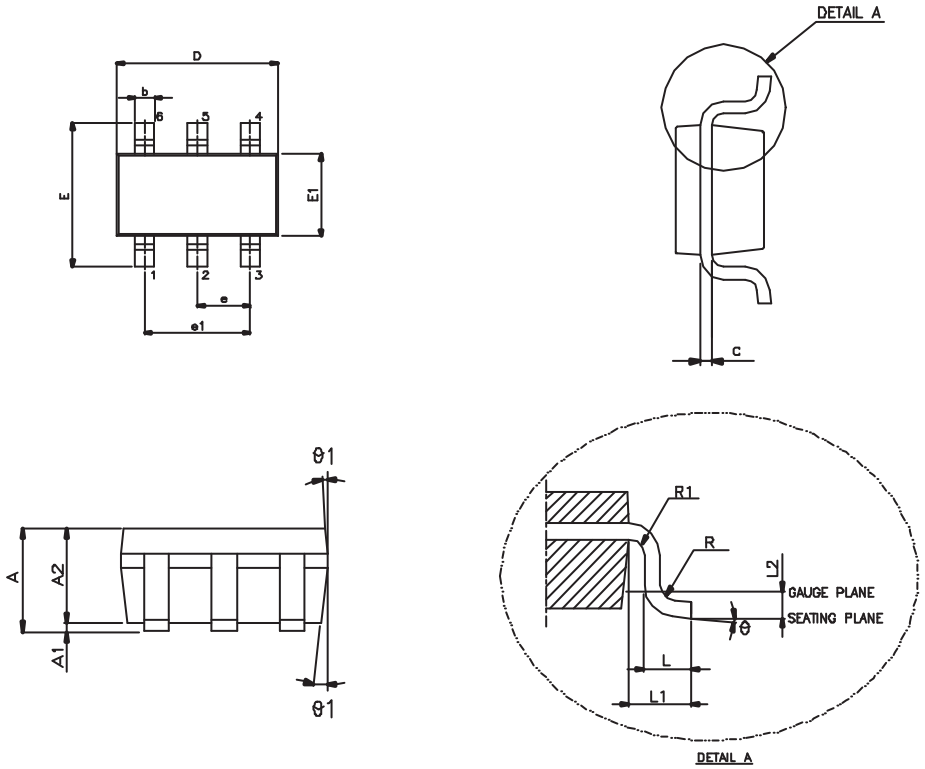
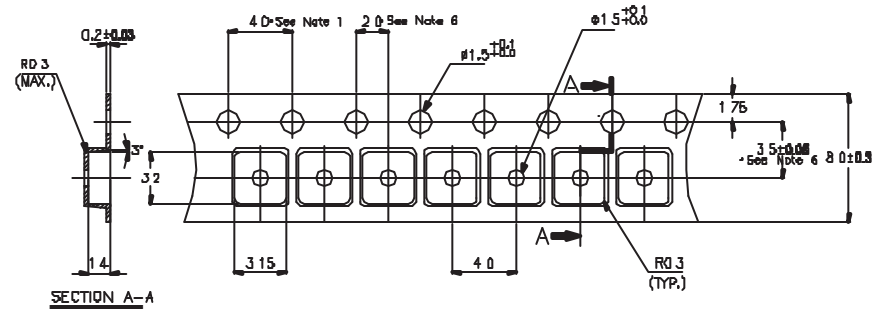


SYMBOL	MIN.	NOM.	MAX.
A	–	–	1.45
A1	–	–	0.15
A2	0.90	1.15	1.30
b	0.30	–	0.50
c	0.08	–	0.22
D		2.90 BSC.	
E		2.80 BSC.	
E1		1.60 BSC.	
e		0.95 BSC	
e1		1.90 BSC.	
L	0.30	0.45	0.60
L1		0.60 REF.	
L2		0.25 BSC.	
R	0.10	–	–
R1	0.10	–	0.25
θ	0°	4°	8°
θ1	5°	10°	15°

TSOP6 Tape and Reel Data

TSOP6 Carrier Tape



TSOP6 Reel